



Lead-Free Solder Paste

PF602-P26

Rev. 2017/06/19 Ver. 02-01

BASIC OVERVIEW



BiSn42 Solder Paste
Halide Free
No Clean
Low Melting Point

APPLICATIONS

Low Melting Point Lead-Free SMD Solder Paste
Wide Range of Applications and PCB designs

FEATURES

Appearance	Gray paste w/o visible foreign and clusters	
Alloy Composition	BiSn42	JIS-Z-3282
Melting Point	139 °C	
Particle Size	(Type 3) +45μm < 1% , - 20μm < 10% (Type 4) +38μm < 1% , - 20μm < 10%	J-STD-005
Powder Shape	Spherical	
Flux Content	10.5 ± 1.0 wt%	JIS-Z-3197, 8.1.2
Viscosity	180 ± 50 Pa.s (25±1°C, 10rpm, Malcom)	JIS-Z-3284 Annex 6
Flux Type	ROLO	J-STD-004

Alloy Detail Composition

(Bi)	(Sn)	(Ag)	(Cu)	(Ni)	(Zn)	(Al)	(Sb)	(Fe)	(As)	(Cd)	(Au)	(Pb)
REM.	41~ 43	0.1 MAX	0.05 MAX	0.01 MAX	0.001 MAX	0.001 MAX	0.05 MAX	0.02 MAX	0.03 MAX	0.002 MAX	0.05 MAX	0.05 MAX

(wt%)

Scan Code for Solder
Paste Documents





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PERFORMANCE & RELIABILITY

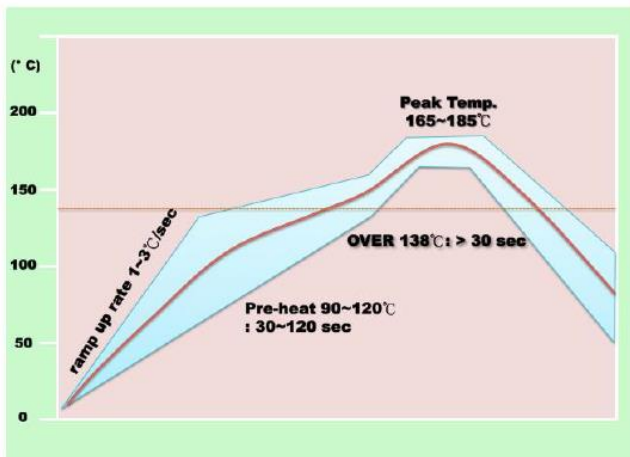
Copper Plate Corrosion Test	Pass	IPC-TM-650, 2.6.15
Halogen Content Test	ROLO	BS EN14582
Copper Mirror Test	Pass	IPC-TM-650, 2.3.32
Viscosity Test (25°C, 10 rpm)	180 ± 50 Pa.s	JIS-Z-3284, Annex 6
Spreading Test	> 70%	JIS-Z-3197, 8.3.1.1
Tackiness Test (gf)	> 130 (8hr)	JIS-Z-3284, Annex 9
Slump Test	Pass	JIS-Z-3284, Annex 7,8
Solder Ball Test	Pass	JIS-Z-3284, Annex 11

S.I.R. Test	▲	Pass	IPC-TM-650, 2.6.3.3
Electro Migration Test	◆	Pass	IPC-TM-650, 2.6.14.1

▲ Test Conditions : 85 °C, 85% RH for 168hrs

◆ Test Conditions: 65°C, 88.5% RH for 596 hrs

RECOMMENDED REFLOW PROFILE



Ramp Up Rate (30-90°C): 1.0-3.0 °C/sec

Pre-heating Time (90-120°C): 30-120 sec

Time Period Above 138°C: >30 sec

Peak Temperature: 165-185 °C

Ramp Down Cooling Rate: 1.0-6.0 °C/sec

Note: The recommended reflow profile is provided as a guideline. Optimal profile may differ due to oven type, assembly layout or other process variables.



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STORAGE & HANDLING:

- Refrigerate the solder paste at 0-10°C. Shelf life is 6 months from production date (sealed package).
- Keep away of direct sunlight.
- Allow the paste to reach defined printing temperature (room temperature) for 3-4 hrs. Do not heat up the solder paste rapidly.
- For jars packaging, mix the solder paste before use for 1-3 mins by plastic spatula.
- It is recommended to finish fresh paste within 24 hrs. Do not store used paste and fresh paste in the same jar.
- If printing process was interrupted for more than 1 hour, remove the remained paste from stencil and seal in the jar.
- Recommended printing environment is 22-28°C and RH 30-60%.

Note: For more information, please refer to solder paste application guideline sheet

HOW TO ORDER

PF602 – P26 – T3 – 500

Solder Alloy
PF602 = BiSn42

Flux
P26 = ROL0

Particle Size
T3 = 20-45µm
T4 = 20-38µm

Weight / Packaging
30 = syringe 30g
100 = syringe 100g
150 = syringe 150g
250 = plastic jar 250g
500 = plastic jar 500g
600 = small cartridge 600g
1200 = large cartridge 1200g



CONTACTS

Tel.: +49-152-5106-5427


support@nevo-solder.com

www.nevo-solder.com

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NeVo®, Škrobárenská 506/2, 617 00 BRNO, CZECH REPUBLIC